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CSTIC 2023 Summary

June 26-July 27, 2023

Shanghai, China

www.semiconchina.org/cstic v.semi.org.cn/cstic



Plenary Session and Award Winners



Plenary Speakers

2023 CSTIConference, June 26-27, 2023, Shanghai
Albert Fert, Université Paris-Saclay, Umr CNRS-Thales

Switching greener with spintronics and **prospects far beyond**

Thanks to my coworkers at UMR CNRS/Thales at Université Paris-Saclay
and acknowledgements of collaborations



SPINTEC, Grenoble, Un. de Lorraine, Nancy,
Beihang University, Beijing, China
Colorado St. Un., Fort Collins, CO, USA
Western Dig. Corp., San José, CA, USA
Intel Corp., Hillsboro, OR, USA

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Spintronics for Greener Digital Technologies and
Prospects Far Beyond

Prof. Albert Fert

**Research Director, Unité Mixte de Physique,
Nobel Laureate in 2007**

Innovations Boost Integrated Circuit

Prof. Ming Liu

Academician of CAS, Fudan University

Advanced Packaging Technology Challenges: an
Equipment Supplier's Perspective

Dr. Yang Pan

Corporate Vice President, Lam Research

Endless Technological Innovation in IC Equipment

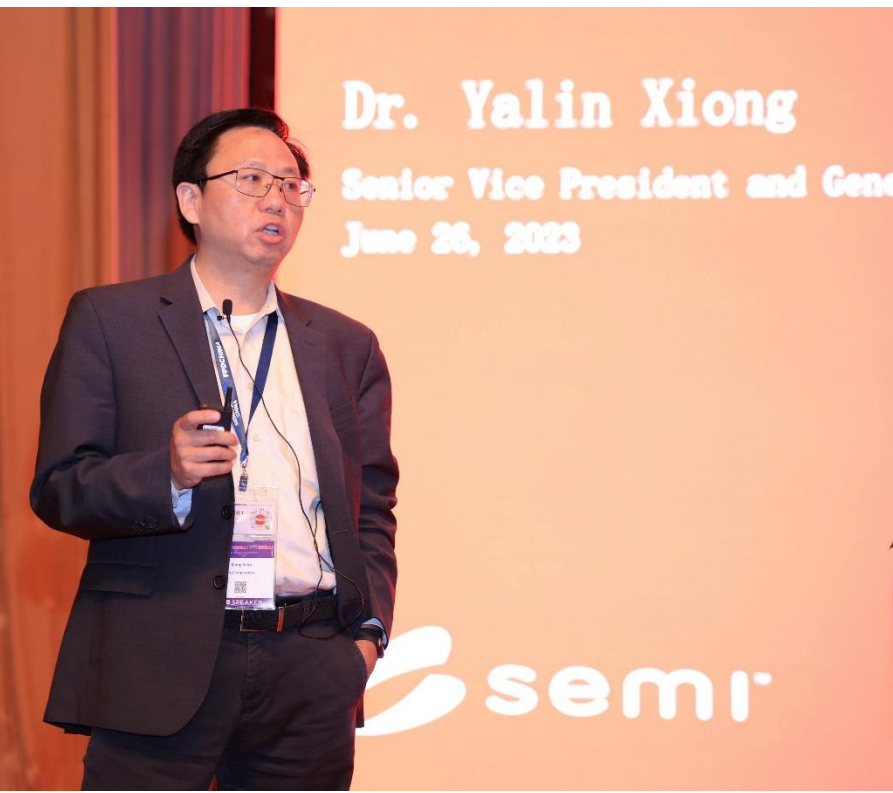
Mr. Jinrong Zhao

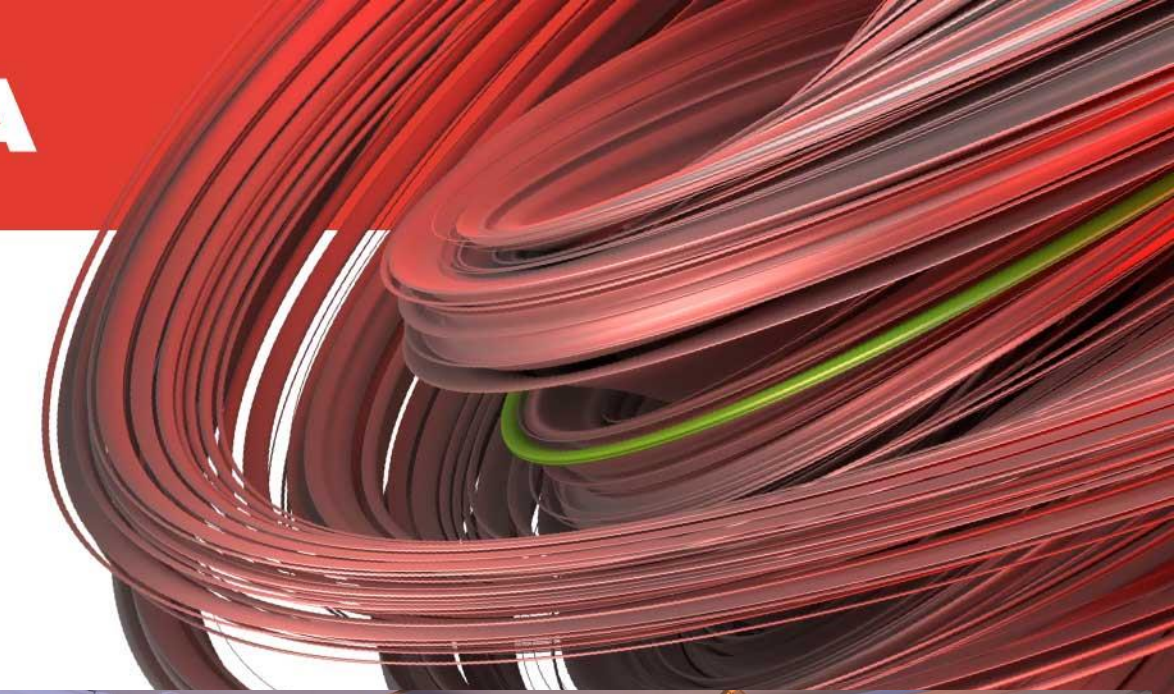
**Chairman of the Executive Committee, Beijing
NAURA Technology Group**

From Legacy to Leading Edge: Broadband Wafer
Optical Inspection for Process Control

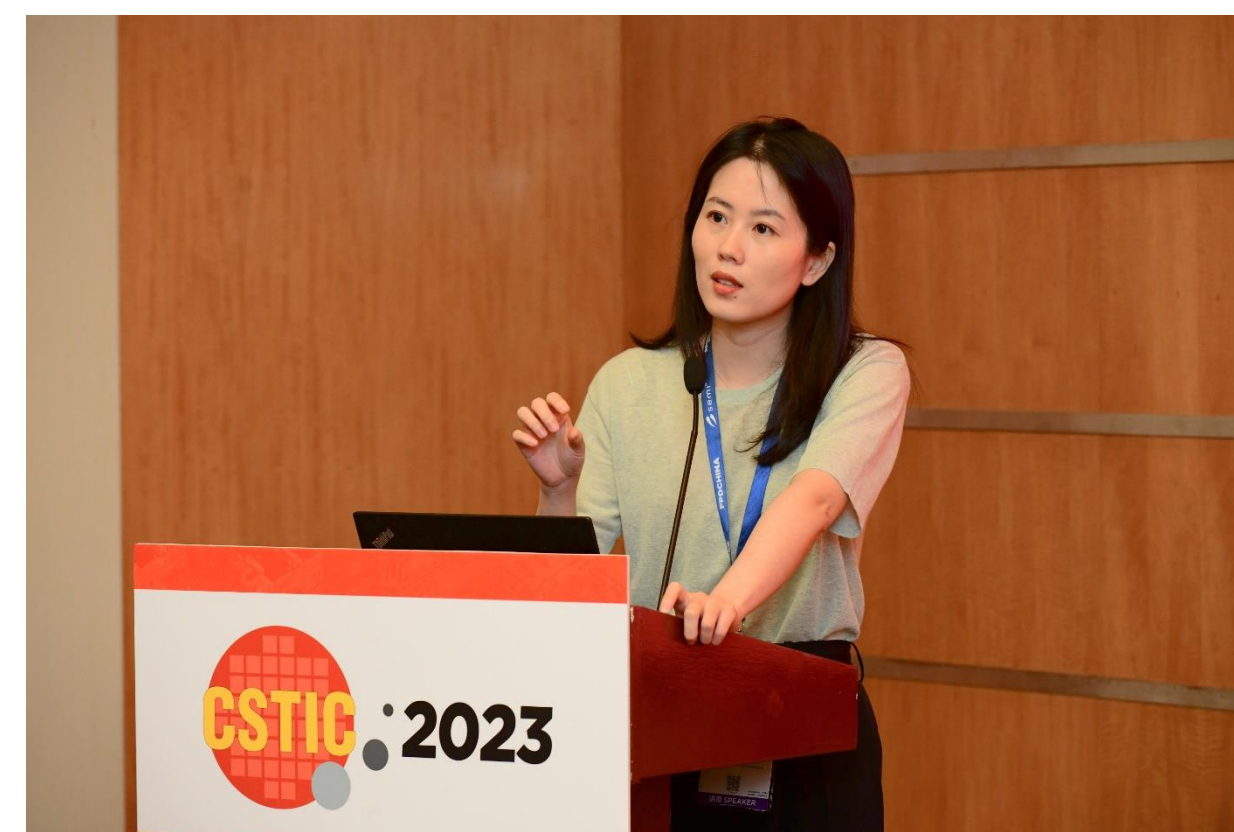
Dr. Yalin Xiong

**Senior Vice President and General Manager, KLA
Corporation**





>170 Oral Presentations and >180 Posters



9 Symposia with 100 Invited Speakers

Symp I: Device Engineering and Memory Technology

Symp. II: Lithography and Patterning

Symp. III: Dry & Wet Etch and Cleaning

Symp. IV: Thin Film, Plating and Process Integration

Symp. V: CMP and Post CMP Cleaning

Symp. VI: Metrology, Reliability and Testing

Symp. VII: Packaging and Assembly

Symp. VIII: MEMS, Sensors and Emerging Semiconductor Technologies

Symp. IX: Design and Automation of Circuits and Systems

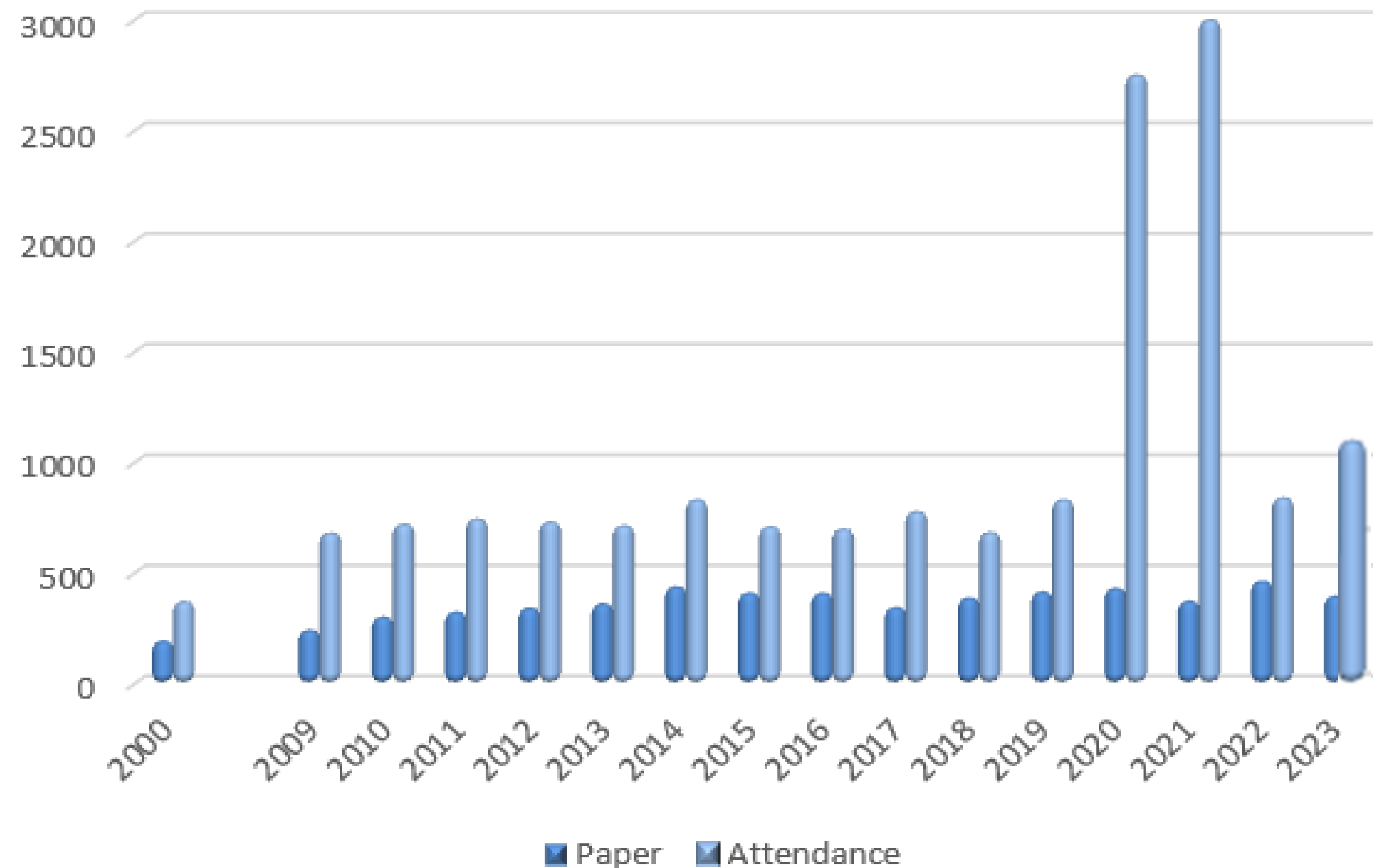
Virtual Conference: June 29-July 26 v.semi.org.cn/cstic

	Zhongrui Wang University of Hong Kong		Mario Lanza King Abdullah University of Science and Technology (KAUST)
	Yasin Ekin Paul Scherrer Institute		Toru Fujimori FUJIFILM Corporation
	Henri van Helleputte ASML Netherlands B.V.		Allen Chang JSR Corporation
	Yunlong Li Zhejiang University	 中国半导体技术大会	
	Yan Sun Beijing NAURA Microelectronics Equipment Co., Ltd		Bing Liu Anji Microelectronics Technology (Shanghai) Co., Ltd
	Hongqi Xiang InvenTech Materials		Huawei Li Institute of Computing Technology, Chinese Academy of Sciences
	Alan Wang Baylor University		Zhen Zhang Uppsala University

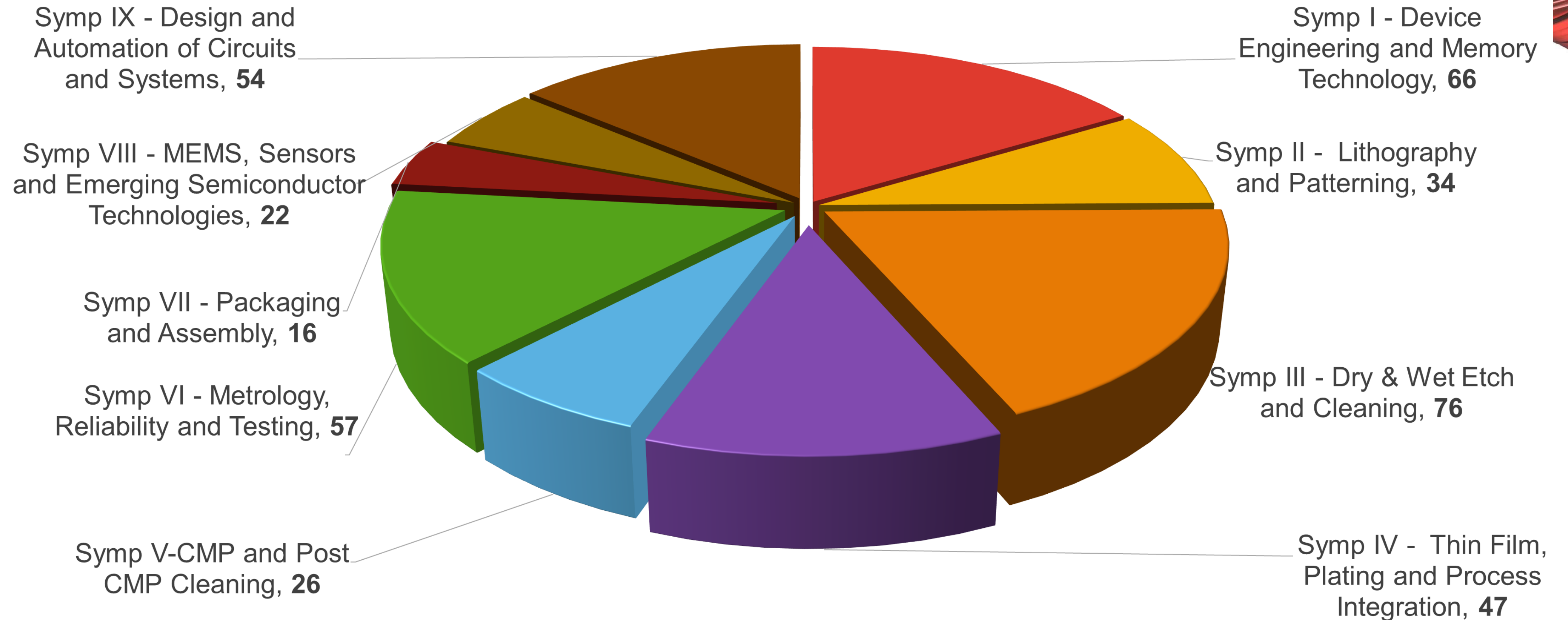
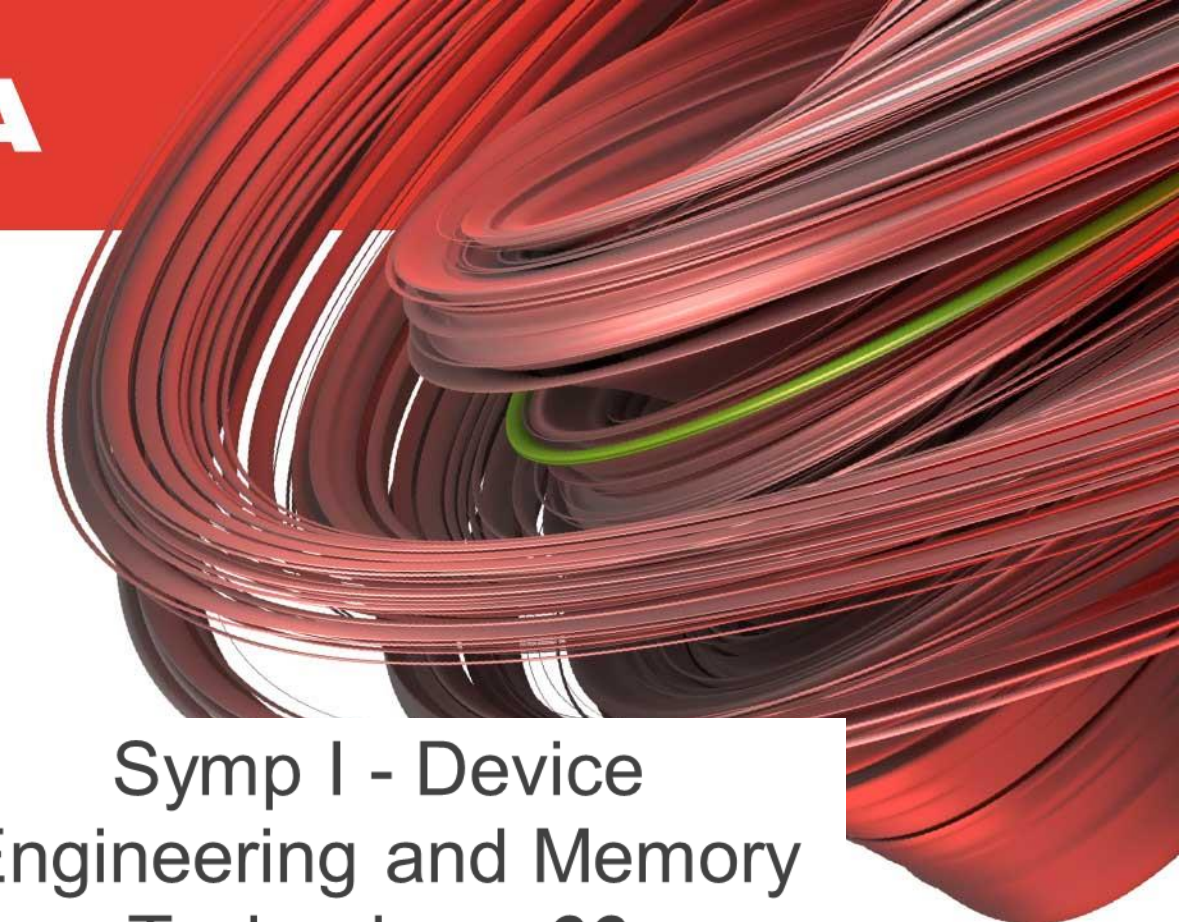


CSTIC 2023

- Largest and most comprehensive, influential annual industrial semiconductor technology conference in China and Asia
- **403 abstract submissions** have been collected. **724 registered attendees joined the onsite conference**, while **online registration is 1061**, including overseas attendees from US, Israel, Japan, Korea, Germany, Sweden, Switzerland, Singapore, UK, Russia, Canada, France, Saudi Arabia, Taiwan China, HK China and etc.



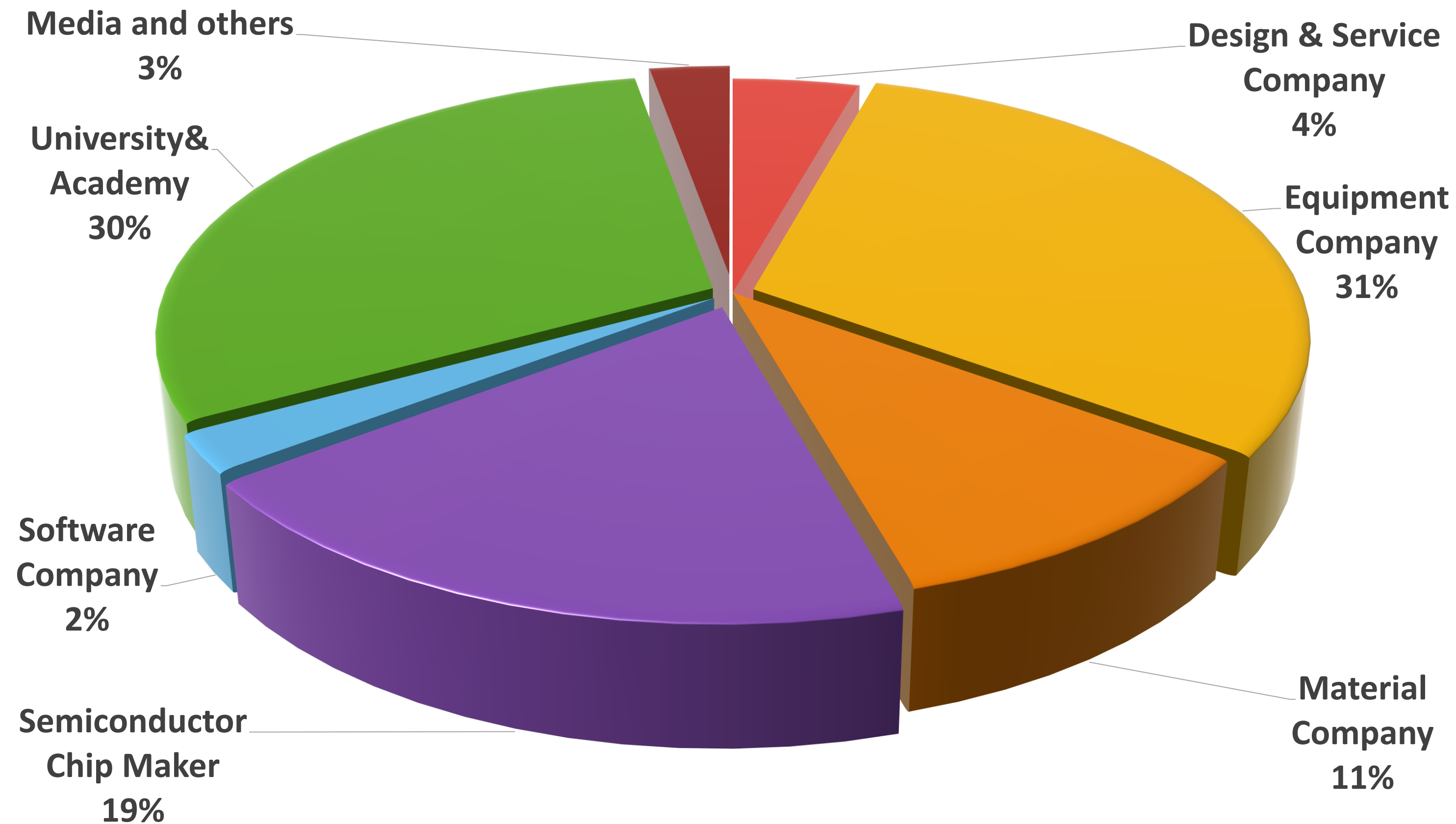
CSTIC Symposium Abstract Submission



**Totally 205 manuscripts published at IEEE*

Industry and Academy Cooperation

67% Attendees from Industry



- 67% attendees from industry
- 30% attendees from academy
- Attendees were from around 190 different companies or institutes
- Chip companies like SMIC, HLMC, HHGrace, JCET, CXMT, CXMC, NXP, Wuhan Xinxin, Intel, AMD and etc. joined the conference

190 Participating Companies

5N Plus China	China University of Politics and Law	Hwatsing Technology
AAA	CXMT	IBM
ACM	Cymer	ICT, CAS
ADVANTEST	D2S Inc.	Ideal Energy Sunflower
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Anji	French institute for Scientific Research	Jiangsu Leadmicro Nano Technology
Applied Materials	Fudan University	Jinan Shengquan Group
ASM	Fujian Jinhua Integrated Circuit	Jinhua Integrated Circuit
ASML	Fujifilm	JSR
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Beijing Jiaotong University	Guangdong University of Technology	Liverpool John Moores University
Beijing Naura	Haohua Gas	Mayair
Beijing NeuCloud	Hebei University of Technology	Mentor Graphics
Beijing Sunrise Technology	HFC Semiconductor	Nanjing Universitiy
Beijing Superstring Memory Research Institute	HHGrace	Nanjing University of Posts and Telecommunications
Beijing University of Chemical Technology	HIKMICRO	National Central University
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190 Participating Companies

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Radiant Shore
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S.Y.Technology Engineering&Construction
Sanechips Technology
School of Integrated Circuits, Chinese Academy of Sciences
Shandong Shengquan New Materials
Shanghai Institute of IC Materials
Shanghai Jiao Tong University
Shanghai United Imaging Healthcare
Shanghai University
Shanghaitech University
Shenzhen China Star Optoelectronics Semiconductor Display Technology
Shenzhen University
Shinko Control Technology
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XMC
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半导体行业观察
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WFD Training Courses

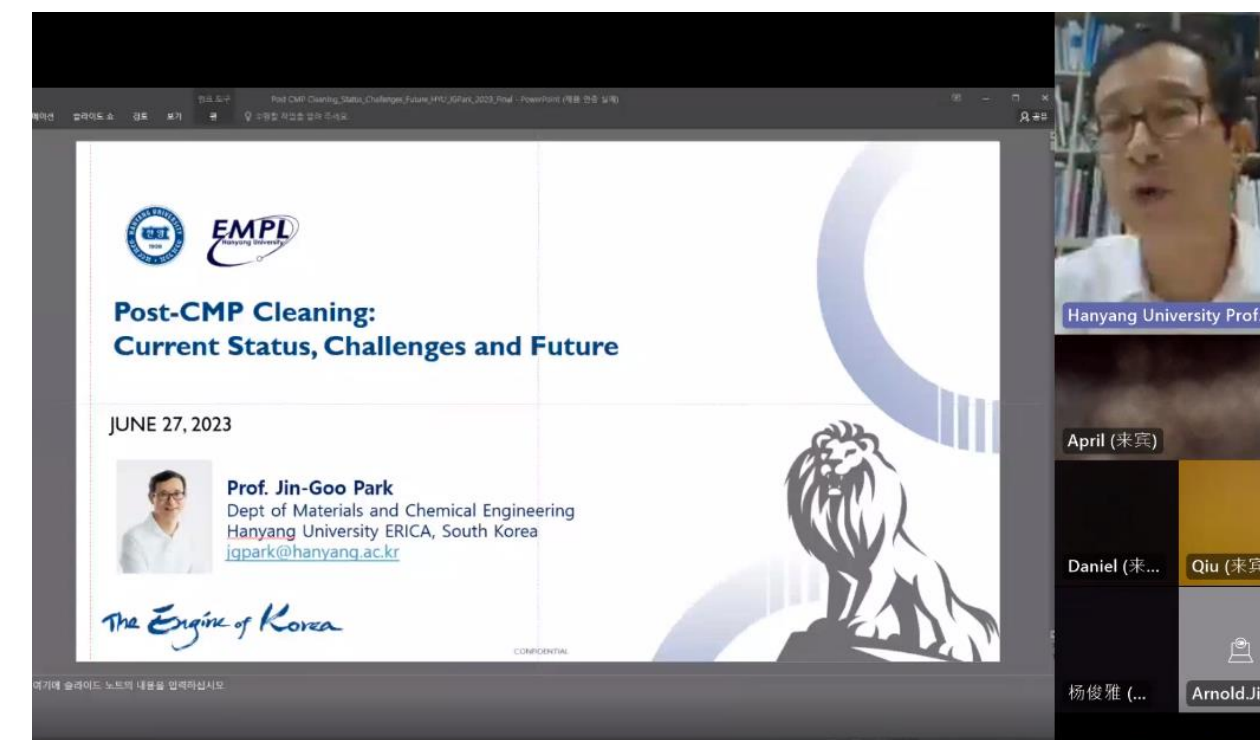
Lithography process and key technical aspects in exposure tools, materials, and the future development roadmap

Dr. Qiang Wu, Professor of the School of Microelectronics of Fudan University



Post CMP Cleaning

Dr. Jin-Goo Park, Professor of Hanyang University, Korea



Attendees to Plenary Session and 9 Symposia

CSTIC 2023 Attendee Number	724
Plenary Session	605
Symp I - Device Engineering and Memory Technology	250
Symp II-III Joint Session	199
Symp II - Lithography and Patterning	235
Symp III - Dry & Wet Etch and Cleaning	314
Symp IV - Thin Film, Plating and Process Integration	389
Symp V - CMP and Post-Polish Cleaning	157
Symp VI - Metrology, Reliability and Testing	143
Symp VII - Packaging and Assembly	77
Symp VIII - MEMS, Sensors and Emerging Semiconductor Technologies	52
Symp IX - Design and Automation of Circuits and Systems	129



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Conference Chair



Dr. Beichao Zhang
Conference Executive
Co-Chair



Prof. Ru Huang
Conference Co-Chair



Prof. Cor Claeys
Conference Co-Chair



Dr. Steve X. Liang
Conference Co-Chair



Dr. Qinghuang Lin
Conference Co-Chair

Symposium Chairs



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Symp-I Chair,
Conference Co-Chair
Professor of Peking
University,
President of Southeast
University,
Academician of Chinese
Academy of Sciences



Dr. Linyong (Leo) Pang
Symp-II Chair
Vice President, D2S Inc.,
USA



Dr. Ying Zhang
Symp-III Chair
Consultant



Dr. Xiaoping Shi
Symp-IV Chair
CTO, Beijing Naura
Microelectronics, China



Dr. Xinping Qu
Symp-V Chair
Professor, Fudan
University, China



Dr. Xiaowei Li
Symp-VI Chair, Deputy
Director, ICT, CAS, China



Dr. Steve X. Liang
Symp-VII Chair



Dr. Qinghuang Lin
Symp-VIII Chair Director,
Lam Research, USA



Prof. Weikang Qian
Symp-IX Chair
Assistant Professor,
University of Michigan-
Shanghai Jiao Tong
University Joint Institute,
China



Dr. Hsiang-Lan Lung
Poster Chair
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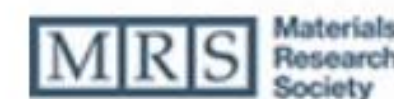
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Proceedings Publication:



CSTIC 2024

Time: March 17 ~ 18, 2024

CSTIC 2024 call for papers and manuscript deadlines:

Abstract Due: Sep. 30, 2023

Author Notification: Oct. 15, 2023

Manuscript Due: Dec. 26, 2023

Copyright Due: Feb. 10, 2024

Presentation Due: Feb. 20, 2024

Conference Date: Mar. 17-18, 2024



Thank you